

| L Numb r | Hits | Search Text | DB | Time stamp |
|---------------------|-------------|---|---|---------------------|
| 1 | 18 | 5665260, 2002/0027130 | USPAT; US-P PUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 13:16 |
| 2 | 8 | (5665260, 2002/0027130) and Ca | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 13:17 |
| 4 | 4 | ((5665260, 2002/0027130) and Ca) and ppm | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 13:18 |
| 3 | 1 | ((5665260, 2002/0027130) and Ca) and weight | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 13:57 |
| 5 | 0 | ((5665260, 2002/0027130) and Ca) and ppm) and Na | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 13:36 |
| 6 | 4 | ((5665260, 2002/0027130) and Ca) and ppm) and B | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 13:25 |
| 7 | 35 | 6475606, 5753893, 5750958, "5721062" | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 13:26 |
| 8 | 22 | (6475606, 5753893, 5750958, "5721062") and weight | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 13:27 |
| 9 | 3 | (6475606, 5753893, 5750958, "5721062") and weight with ppm | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 13:40 |
| 10 | 0 | ((6475606, 5753893, 5750958, "5721062") and weight) and weight with percntage | USPAT; US-PGPUB; EP ; JP ; DERWENT; IBM_TDB | 2003/08/05 13:32 |

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| 11 | 0 | ((6475606, 5753893, 5750958, "5721062") and weight) and weight with percentage | USPAT; US-PUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 13:40 |
| 12 | 3 | ((6475606, 5753893, 5750958, "5721062") and weight) and weight with percent | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 13:33 |
| 13 | 4 | ((6475606, 5753893, 5750958, "5721062") and weight) and Na | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 13:36 |
| 14 | 98 | ceramic adj heater and Na | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 14:18 |
| 15 | 17 | (ceramic adj heater and Na) and weight with ppm | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 13:40 |
| 16 | 15 | (ceramic adj heater and Na) and weight with percentage | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 13:41 |
| 17 | 6 | ((ceramic adj heater and Na) and weight with ppm) and ((ceramic adj heater and Na) and weight with percentage) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 13:45 |
| 18 | 2 | (ceramic adj heater and Na) and Na with percentage | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 13:49 |
| 19 | 0 | (ceramic adj heater and Na) and y with percentage | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 13:48 |
| 20 | 13 | (ceramic adj heater and Na) and Na with ppm | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 14:12 |

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| 21 | 0 | (6475606, 5753893, 5750958, "5721062") and Li with weight | USPAT; US-PGPUB; EP ; JP ; DERWENT; IBM_TDB | 2003/08/05 13:58 |
| 22 | 0 | (5665260, 2002/0027130) and Li with weight | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 13:58 |
| 23 | 3 | (6475606, 5753893, 5750958, "5721062") and Ca with weight | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 14:03 |
| 24 | 4 | (ceramic adj heater and Na) and Ca with weight | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 14:08 |
| 25 | 2 | (5665260, 2002/0027130) and nitride adj ceramic | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 14:15 |
| 26 | 10 | (6475606, 5753893, 5750958, "5721062") and nitride adj ceramic | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 14:15 |
| 27 | 313501 | ceramic adj heater same semiconductor wafer | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 14:32 |
| 28 | 1 | (ceramic adj heater same semiconductor wafer) and distance | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 14:20 |
| 29 | 57870 | (ceramic adj heater same semiconductor wafer) and distance | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 14:21 |
| 30 | 4339 | ((ceramic adj heater same semiconductor wafer) and distance) and distance same micron | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 14:22 |

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| 31 | 2611 | ((c ramic adj heater sam s miconduct r waf r) and distance) and distance with micron | USPAT; US-P PUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 14:23 |
| 32 | 127 | ((c ramic adj heat r sam s mic nductor wafer) and distance) and distance with one adj micron | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 14:32 |
| 33 | 0 | ((((ceramic adj heater same semiconductor wafer) and distance) and distance with one adj micron) and 219/444 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 14:27 |
| 34 | 0 | ((((ceramic adj heater same semiconductor wafer) and distance) and distance with one adj micron) and ceramic adj substrate with thickness | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 14:25 |
| 35 | 0 | ((((ceramic adj heater same semiconductor wafer) and distance) and distance with one adj micron) and ceramic adj substrate with thermal adj conductivity | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 14:38 |
| 36 | 0 | ((((ceramic adj heater same semiconductor wafer) and distance) and distance with one adj micron) and supporting adj pin | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 14:26 |
| 37 | 2 | ((((ceramic adj heater same semiconductor wafer) and distance) and distance with one adj micron) and 219/\$.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 14:28 |
| 38 | 2 | ((((ceramic adj heater same semiconductor wafer) and distance) and distance with one adj micron) and 428/\$.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 14:30 |
| 39 | 47 | ((((ceramic adj heater same semiconductor wafer) and distance) and distance with one adj micron) and heat\$3 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 14:34 |
| 40 | 181 | ceramic adj heater same semiconductor adj wafer | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 14:32 |

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| 41 | 0 | (c ramic adj h at r same s mic nductor adj wafer) and distance with n adj micr n | USPAT; US-PGPUB; EP ; JPO; DERWENT; IBM_TDB | 2003/08/05 15:30 |
| 42 | 0 | (c ramic adj h ater sam s mic nductor adj wafer) and distance with ten adj micron | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 14:33 |
| 43 | 0 | (ceramic adj heater same semiconductor adj wafer) and distance with fifty adj micron | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 14:35 |
| 44 | 181 | (ceramic adj heater same semiconductor adj wafer) and heat\$3 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 14:34 |
| 45 | 0 | (ceramic adj heater same semiconductor adj wafer) and one adj micron | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 14:34 |
| 46 | 0 | (ceramic adj heater same semiconductor adj wafer) and distance with micron | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 14:36 |
| 47 | 0 | (ceramic adj heater same semiconductor adj wafer) and apart with micron | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 14:36 |
| 48 | 495 | ceramic adj substrate with thermal adj conductivity | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 14:38 |
| 49 | 38 | (ceramic adj substrate with thermal adj conductivity) and ceramic adj heater | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 14:38 |
| 50 | 172771 | ((ceramic adj substrate with thermal adj conductivity) and ceramic adj heater) and ceramic substrate with thickness | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 14:39 |

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| 51 | 29 | ((ceramic adj substrate with thermal adj c nductivity) and c ramic adj h at r) and c ramic adj substrate with thickn ss | USPAT; US-PGPUB; EP ; JPO; DERWENT; IBM_TDB | 2003/08/05 14:39 |
| 52 | 0 | (c ramic adj heat r same semiconductor adj wafer) and distance same one adj micron | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 15:31 |
| 54 | 9 | (ceramic adj heater same semiconductor adj wafer) and distance same apart | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 15:31 |
| 53 | 47 | (ceramic adj heater same semiconductor adj wafer) and distance | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 15:50 |